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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

| Details | |
|--------------------------------|---|
| Product Status | Active |
| Number of LABs/CLBs | 339620 |
| Number of Logic Elements/Cells | 900000 |
| Total RAM Bits | 59234304 |
| Number of I/O | 768 |
| Number of Gates | - |
| Voltage - Supply | 0.87V ~ 0.98V |
| Mounting Type | Surface Mount |
| Operating Temperature | 0°C ~ 100°C (TJ) |
| Package / Case | 1932-BBGA, FCBGA |
| Supplier Device Package | 1932-FCBGA (45x45) |
| Purchase URL | https://www.e-xfl.com/product-detail/intel/10ax090n2f45e2sg |

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



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Intel® Arria® 10 Device Overview

The Intel® Arria® 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

| Market | Applications |
|-----------------------|---|
| Wireless | Channel and switch cards in remote radio heads Mobile backhaul |
| Wireline | 40G/100G muxponders and transponders 100G line cards Bridging Aggregation |
| Broadcast | Studio switches Servers and transport Videoconferencing Professional audio and video |
| Computing and Storage | Flash cache Cloud computing servers Server acceleration |
| Medical | Diagnostic scanners Diagnostic imaging |
| Military | Missile guidance and control Radar Electronic warfare Secure communications |

Related Information

Intel Arria 10 Device Handbook: Known Issues

Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.

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Key Advantages of Intel Arria 10 Devices

Table 2. Key Advantages of the Intel Arria 10 Device Family

| Advantage | Supporting Feature |
|---|---|
| Enhanced core architecture | Built on TSMC's 20 nm process technology 60% higher performance than the previous generation of mid-range FPGAs 15% higher performance than the fastest previous-generation FPGA |
| High-bandwidth integrated transceivers | Short-reach rates up to 25.8 Gigabits per second (Gbps) Backplane capability up to 12.5 Gbps Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC) |
| Improved logic integration and hard IP blocks | 8-input adaptive logic module (ALM) Up to 65.6 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks Fractional synthesis phase-locked loops (PLLs) Hard PCI Express Gen3 IP blocks Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps) |
| Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor | Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric |
| Advanced power savings | Comprehensive set of advanced power saving features Power-optimized MultiTrack routing and core architecture Up to 40% lower power compared to previous generation of mid-range FPGAs Up to 60% lower power compared to previous generation of high-end FPGAs |

Summary of Intel Arria 10 Features

Table 3. Summary of Features for Intel Arria 10 Devices

| Feature | Description |
|---------------------------------|---|
| Technology | TSMC's 20-nm SoC process technology Allows operation at a lower V_{CC} level of 0.82 V instead of the 0.9 V standard V_{CC} core voltage |
| Packaging | 1.0 mm ball-pitch Fineline BGA packaging 0.8 mm ball-pitch Ultra Fineline BGA packaging Multiple devices with identical package footprints for seamless migration between different FPGA densities Devices with compatible package footprints allow migration to next generation high-end Stratix® 10 devices RoHS, leaded⁽¹⁾, and lead-free (Pb-free) options |
| High-performance FPGA fabric | Enhanced 8-input ALM with four registers Improved multi-track routing architecture to reduce congestion and improve compilation time Hierarchical core clocking architecture Fine-grained partial reconfiguration |
| Internal memory blocks | M20K—20-Kb memory blocks with hard error correction code (ECC) Memory logic array block (MLAB)—640-bit memory |
| | continued |

⁽¹⁾ Contact Intel for availability.



Available Options

Figure 1. Sample Ordering Code and Available Options for Intel Arria 10 GX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



Maximum Resources

Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)

| Resc | ource | | | Product Line | | |
|------------------------------|-------------------------|---------|---------|---------------------|---------|---------|
| | | GX 160 | GX 220 | GX 270 | GX 320 | GX 480 |
| Logic Elements | (LE) (K) | 160 | 220 | 270 | 320 | 480 |
| ALM | | 61,510 | 80,330 | 101,620 | 119,900 | 183,590 |
| Register | | 246,040 | 321,320 | 406,480 | 479,600 | 734,360 |
| Memory (Kb) | M20K | 8,800 | 11,740 | 15,000 | 17,820 | 28,620 |
| | MLAB | 1,050 | 1,690 | 2,452 | 2,727 | 4,164 |
| Variable-precision DSP Block | | 156 | 192 | 830 | 985 | 1,368 |
| 18 x 19 Multipli | er | 312 | 384 | 1,660 | 1,970 | 2,736 |
| PLL | Fractional Synthesis | 6 | 6 | 8 | 8 | 12 |
| | I/O | 6 | 6 | 8 | 8 | 12 |
| 17.4 Gbps Trans | sceiver | 12 | 12 | 24 | 24 | 36 |
| GPIO (3) | | 288 | 288 | 384 | 384 | 492 |
| LVDS Pair (4) | | 120 | 120 | 168 | 168 | 222 |
| PCIe Hard IP Block | | 1 | 1 | 2 | 2 | 2 |
| Hard Memory C | ontroller | 6 | 6 | 8 | 8 | 12 |

 $^{^{(3)}}$ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁴⁾ Each LVDS I/O pair can be used as differential input or output.



Table 6. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

| Re | source | | Produc | t Line | |
|------------------------------|------------|---------|-----------|-----------|-----------|
| | | GX 570 | GX 660 | GX 900 | GX 1150 |
| Logic Elements | s (LE) (K) | 570 | 660 | 900 | 1,150 |
| ALM | | 217,080 | 251,680 | 339,620 | 427,200 |
| Register | | 868,320 | 1,006,720 | 1,358,480 | 1,708,800 |
| Memory (Kb) | M20K | 36,000 | 42,620 | 48,460 | 54,260 |
| | MLAB | 5,096 | 5,788 | 9,386 | 12,984 |
| Variable-precision DSP Block | | 1,523 | 1,687 | 1,518 | 1,518 |
| 18 x 19 Multip | lier | 3,046 | 3,374 | 3,036 | 3,036 |
| PLL Fractional Synthesis | | 16 | 16 | 32 | 32 |
| | I/O | 16 | 16 | 16 | 16 |
| 17.4 Gbps Trai | nsceiver | 48 | 48 | 96 | 96 |
| GPIO (3) | | 696 | 696 | 768 | 768 |
| LVDS Pair (4) | | 324 | 324 | 384 | 384 |
| PCIe Hard IP Block | | 2 | 2 | 4 | 4 |
| Hard Memory | Controller | 16 | 16 | 16 | 16 |

Package Plan

Table 7. Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

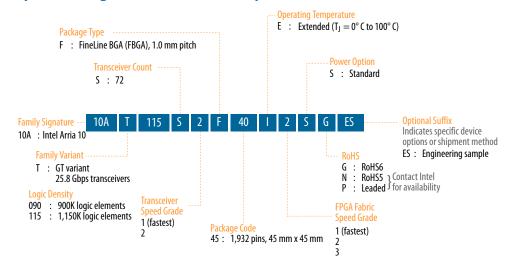
Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

| Product Line | U19 (19 mm × 19 mm, 484-pin UBGA) | | (19 mm × 19 mm, (27 mm × 27 mm, | | F29 (29 mm × 29 mm, 780-pin FBGA) | | | | |
|--------------|---|----------|---------------------------------|---------|---|------|---------|----------|------|
| | 3 V I/O | LVDS I/O | XCVR | 3 V I/O | LVDS I/O | XCVR | 3 V I/O | LVDS I/O | XCVR |
| GX 160 | 48 | 192 | 6 | 48 | 192 | 12 | 48 | 240 | 12 |
| GX 220 | 48 | 192 | 6 | 48 | 192 | 12 | 48 | 240 | 12 |
| GX 270 | _ | _ | _ | 48 | 192 | 12 | 48 | 312 | 12 |
| GX 320 | _ | _ | _ | 48 | 192 | 12 | 48 | 312 | 12 |
| GX 480 | _ | _ | _ | _ | _ | _ | 48 | 312 | 12 |



Available Options

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices





Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 SX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.

Available Options

Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



| Variant | Product Line | Variable- precision DSP Block | Independent In Multiplication | | 18 x 19 Multiplier | 18 x 18 Multiplier Adder | | |
|---------|--------------|-------------------------------------|----------------------------------|-------|-----------------------|--------------------------------|-------------------|--------------------------|
| | | DSI BIOCK | 18 x 19 27 x 27 | | | | Adder Sum Mode | Summed with 36 bit Input |
| | SX 320 | 984 | 1,968 | 984 | 984 | 984 | | |
| | SX 480 | 1,368 | 2,736 | 1,368 | 1,368 | 1,368 | | |
| | SX 570 | 1,523 | 3,046 | 1,523 | 1,523 | 1,523 | | |
| | SX 660 | 1,687 | 3,374 | 1,687 | 1,687 | 1,687 | | |

Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

| Variant | Product Line | Variable- precision DSP Block | Single Precision Floating-Point Multiplication Mode | Single-Precision Floating-Point Adder Mode | Single- Precision Floating-Point Multiply Accumulate Mode | Peak Giga Floating- Point Operations per Second (GFLOPs) |
|----------------|--------------|-------------------------------------|---|--|--|--|
| Intel Arria 10 | GX 160 | 156 | 156 | 156 | 156 | 140 |
| GX | GX 220 | 192 | 192 | 192 | 192 | 173 |
| | GX 270 | 830 | 830 | 830 | 830 | 747 |
| | GX 320 | 984 | 984 | 984 | 984 | 886 |
| | GX 480 | 1,369 | 1,368 | 1,368 | 1,368 | 1,231 |
| | GX 570 | 1,523 | 1,523 | 1,523 | 1,523 | 1,371 |
| | GX 660 | 1,687 | 1,687 | 1,687 | 1,687 | 1,518 |
| | GX 900 | 1,518 | 1,518 | 1,518 | 1,518 | 1,366 |
| | GX 1150 | 1,518 | 1,518 | 1,518 | 1,518 | 1,366 |
| Intel Arria 10 | GT 900 | 1,518 | 1,518 | 1,518 | 1,518 | 1,366 |
| GT | GT 1150 | 1,518 | 1,518 | 1,518 | 1,518 | 1,366 |
| Intel Arria 10 | SX 160 | 156 | 156 | 156 | 156 | 140 |
| SX | SX 220 | 192 | 192 | 192 | 192 | 173 |
| | SX 270 | 830 | 830 | 830 | 830 | 747 |
| | SX 320 | 984 | 984 | 984 | 984 | 886 |
| | SX 480 | 1,369 | 1,368 | 1,368 | 1,368 | 1,231 |
| | SX 570 | 1,523 | 1,523 | 1,523 | 1,523 | 1,371 |
| | SX 660 | 1,687 | 1,687 | 1,687 | 1,687 | 1,518 |

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



Embedded Memory Configurations for Single-port Mode

Table 19. Single-port Embedded Memory Configurations for Intel Arria 10 Devices

This table lists the maximum configurations supported for single-port RAM and ROM modes.

| Memory Block | Depth (bits) | Programmable Width |
|--------------|--------------|--------------------|
| MLAB | 32 | x16, x18, or x20 |
| | 64 (10) | x8, x9, x10 |
| M20K | 512 | x40, x32 |
| | 1K | x20, x16 |
| | 2K | x10, x8 |
| | 4K | x5, x4 |
| | 8K | x2 |
| | 16K | x1 |

Clock Networks and PLL Clock Sources

The clock network architecture is based on Intel's global, regional, and peripheral clock structure. This clock structure is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

Clock Networks

The Intel Arria 10 core clock networks are capable of up to 800 MHz fabric operation across the full industrial temperature range. For the external memory interface, the clock network supports the hard memory controller with speeds up to 2,400 Mbps in a quarter-rate transfer.

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

Fractional Synthesis and I/O PLLs

Intel Arria 10 devices contain up to 32 fractional synthesis PLLs and up to 16 I/O PLLs that are available for both specific and general purpose uses in the core:

- Fractional synthesis PLLs—located in the column adjacent to the transceiver blocks
- I/O PLLs-located in each bank of the 48 I/Os

Fractional Synthesis PLLs

You can use the fractional synthesis PLLs to:

- Reduce the number of oscillators that are required on your board
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

⁽¹⁰⁾ Supported through software emulation and consumes additional MLAB blocks.

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The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
 - Conventional integer mode equivalent to the general purpose PLL
 - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
 - $-\$ Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
 - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V_{OD}) and programmable pre-emphasis



- Series (R_S) and parallel (R_T) on-chip termination (OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Interface

Intel Arria 10 devices offer massive external memory bandwidth, with up to seven 32-bit DDR4 memory interfaces running at up to 2,400 Mbps. This bandwidth provides additional ease of design, lower power, and resource efficiencies of hardened high-performance memory controllers.

The memory interface within Intel Arria 10 FPGAs and SoCs delivers the highest performance and ease of use. You can configure up to a maximum width of 144 bits when using the hard or soft memory controllers. If required, you can bypass the hard memory controller and use a soft controller implemented in the user logic.

Each I/O contains a hardened DDR read/write path (PHY) capable of performing key memory interface functionality such as read/write leveling, FIFO buffering to lower latency and improve margin, timing calibration, and on-chip termination.

The timing calibration is aided by the inclusion of hard microcontrollers based on Intel's Nios® II technology, specifically tailored to control the calibration of multiple memory interfaces. This calibration allows the Intel Arria 10 device to compensate for any changes in process, voltage, or temperature either within the Intel Arria 10 device itself, or within the external memory device. The advanced calibration algorithms ensure maximum bandwidth and robust timing margin across all operating conditions.

In addition to parallel memory interfaces, Intel Arria 10 devices support serial memory technologies such as the Hybrid Memory Cube (HMC). The HMC is supported by the Intel Arria 10 high-speed serial transceivers which connect up to four HMC links, with each link running at data rates up to 15 Gbps.

Related Information

External Memory Interface Spec Estimator

Provides a parametric tool that allows you to find and compare the performance of the supported external memory interfaces in IntelFPGAs.

Memory Standards Supported by Intel Arria 10 Devices

The I/Os are designed to provide high performance support for existing and emerging external memory standards.



Related Information

Intel Arria 10 Device Datasheet

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

PCIe Gen1, Gen2, and Gen3 Hard IP

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

Related Information

PCS Features on page 30

Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet

Interlaken Support

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

Related Information

PCS Features on page 30

10 Gbps Ethernet Support

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.

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The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

Related Information

PCS Features on page 30

Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed



| Protocol | Data Rate (Gbps) | Transceiver IP | PCS Support |
|----------------------|-------------------------------|----------------|--------------|
| CPRI 6.0 (64B/66B) | 0.6144 to 10.1376 | Native PHY | Enhanced PCS |
| CPRI 4.2 (8B/10B) | 0.6144 to 9.8304 | Native PHY | Standard PCS |
| OBSAI RP3 v4.2 | 0.6144 to 6.144 | Native PHY | Standard PCS |
| SD-SDI/HD-SDI/3G-SDI | 0.143 ⁽¹²⁾ to 2.97 | Native PHY | Standard PCS |

Related Information

Intel Arria 10 Transceiver PHY User Guide

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

SoC with Hard Processor System

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

⁽¹²⁾ The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA) Advanced eXtensible Interface (AXI $^{\text{\tiny M}}$) specifications, consist of the following bridges:

- FPGA-to-HPS AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA Avalon/AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows
 the HPS to issue transactions to soft peripherals in the FPGA fabric. This bridge is
 primarily used for control and status register (CSR) accesses to peripherals in the
 FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

The HPS SDRAM controller supports up to 3 masters (command ports), 3x 64-bit read data ports and 3x 64-bit write data ports.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features.



FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
 partially reconfigure the FPGA fabric at any time under software control. The HPS
 can also configure other FPGAs on the board through the FPGA configuration
 controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux*, VxWorks*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



The optional power reduction techniques in Intel Arria 10 devices include:

- SmartVID—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V_{CC} while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- **Low Static Power Options**—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

Incremental Compilation

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

Document Revision History for Intel Arria 10 Device Overview

| Document Version | Changes |
|---------------------|--|
| 2018.04.09 | Updated the lowest V_{CC} from 0.83 V to 0.82 V in the topic listing a summary of the device features. |

| Date | Version | Changes |
|--------------|------------|--|
| January 2018 | 2018.01.17 | Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps. |
| | | Updated maximum frequency supported for half rate QDRII and QDRII + SRAM to 633 MHz in Memory Standards Supported by the Soft Memory Controller table. |
| | | Updated transceiver backplane capability to 12.5 Gbps. |
| | | Removed transceiver speed grade 5 in Sample Ordering Core and Available Options for Intel Arria 10 GX Devices figure. |
| | · | continued |



| Date | Version | Changes |
|----------------|------------|---|
| December 2015 | 2015.12.14 | Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb. |
| | | Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources. |
| November 2015 | 2015.11.02 | • Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660. |
| | | Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in Number of Multipliers in Intel Arria 10 Devices table. |
| | | Updated the available options for Arria 10 GX, GT, and SX. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>. |
| June 2015 | 2015.06.15 | Corrected label for Intel Arria 10 GT product lines in the vertical migration figure. |
| May 2015 | 2015.05.15 | Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller. |
| May 2015 | 2015.05.04 | Added support for 13.5G JESD204b in the Summary of Features table. Added support for 13.5G JESD204b in the Summary of Features table. |
| | | Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic. |
| | | Added a note to the table, Maximum Resource Counts for Arria 10 GT devices. |
| | | Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic. |
| January 2015 | 2015.01.23 | Added floating point arithmetic features in the Summary of Features table. |
| | | Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb. |
| | | Updated the table that lists the memory standards supported by Intel Arria 10 devices. |
| | | Removed support for DDR3U, LPDDR3 SDRAM, RLDRAM 2, and DDR2. Moved RLDRAM 3 support from hard memory controller to soft memory controller. RLDRAM 3 support uses hard PHY with soft memory controller. |
| | | Added soft memory controller support for QDR IV. |
| | | Updated the maximum resource count table to include the number of hard memory controllers available in each device variant. |
| | | Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps. |
| | | Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz. |
| | | Added a feature for fractional synthesis PLLs: PLL cascading. |
| | | Updated the HPS programmable general-purpose I/Os from 54 to 62. |
| September 2014 | 2014.09.30 | Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX. |
| | | Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660. |
| | | Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150. |
| | | continued |

Intel® Arria® 10 Device Overview

A10-OVERVIEW | 2018.04.09



| Date | Version | Changes |
|---------------|------------|---|
| August 2014 | 2014.08.18 | Updated Memory (Kb) M20K maximum resources for Arria 10 GX 660 devices from 42,660 to 42,620. |
| | | Added GPIO columns consisting of LVDS I/O Bank and 3V I/O Bank in the Package Plan table. |
| | | Added how to use memory interface clock frequency higher than 533 MHz in the I/O vertical migration. |
| | | Added information to clarify that RLDRAM3 support uses hard PHY with soft memory controller. |
| | | Added variable precision DSP blocks support for floating-point arithmetic. |
| June 2014 | 2014.06.19 | Updated number of dedicated I/Os in the HPS block to 17. |
| February 2014 | 2014.02.21 | Updated transceiver speed grade options for GT devices in Figure 2. |
| February 2014 | 2014.02.06 | Updated data rate for Arria 10 GT devices from 28.1 Gbps to 28.3 Gbps. |
| December 2013 | 2013.12.10 | Updated the HPS memory standards support from LPDDR2 to LPDDR3. Updated HPS block diagram to include dedicated HPS I/O and FPGA Configuration blocks as well as repositioned SD/SDIO/MMC, DMA, SPI and NAND Flash with ECC blocks . |
| December 2013 | 2013.12.02 | Initial release. |